

# APPROVAL SHEET

# WA06W\_N ±5%, ±1% Convex Type General purpose chip resistors array Size 1506 (3816) 16p8R

Customer Approval No

Issue Date

Customer Approval :



# FEATURE

- 1. Small size and light weight
- 2. Reduced size of final equipment
- 3. Lower surface mounted assembly costs
- 4. Higher component and equipment reliability
- 5. RoHS compliant and Lead (Pb) free, Halogen free

# APPLICATION

- Consumer electrical equipment
- EDP, Computer application
- Telecom

#### DESCRIPTION

The resistors array is constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance by laser cutting of this resistive layer.

The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin (Pb free) solder alloy.

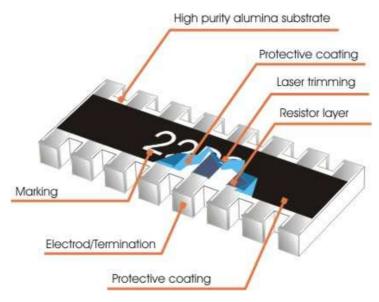


Fig 1. Construction of a Chip-R array WA06W\_N

# QUICK REFERENCE DATA

Item	General Specification			
Series No.	WA06W_N			
Size	1506 (0602x8)			
Termination construction	Convex type			
Resistance Tolerance	±5%, ±1% (E24/E96 series)			
Resistance Range	10 $\Omega$ ~ 100KΩ, Jumper			
TCR (ppm/°C)	≤ ± 200 ppm/°C			
Max. dissipation at T <sub>amb</sub> =70°C	1/16 W			
Max. Operation Voltage (DC or RMS)	25V			
Max. overload voltage	50V			
Climatic category (IEC 60068)	55/125/56			

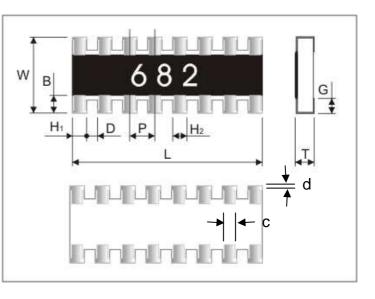
Note :

- 1. This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"
- 2. Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by

 $RCWV = \sqrt{Rated Power \times Resistance Value}$  or Max. RCWV listed above, whichever is lower.

## Dimensions (mm)

	WA06W_N				
L	 3.80 ± 0.10				
W	1.60 ± 0.10				
т	$0.45\pm0.10$				
В	0.30 ± 0.10				
G	0.30 ± 0.10				
D	$0.20\pm0.10$				
Р	0.50 ± 0.10				
H1	$0.30\pm0.10$				
H2	$0.30\pm0.10$				
с	$0.20\pm0.10$				
d	Min. 0.03				



#### Marking

Each resistor is marked with a three-digit code on the protective coating to designate the nominal resistance value of E24 series. There is no marking for resistance value of E96 series !

Example:

$$100 = 10\Omega$$
  
 $101 = 100\Omega$ 

# FUNCTIONAL DESCRIPTION

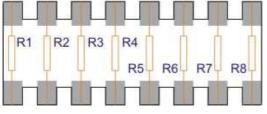
#### Product characterization

Standard values of nominal resistance are taken from the E24/E96 series for resistors with a tolerance of  $\pm 5\%$ ,  $\pm 1\%$ . The values of the E24/E96 series are in accordance with "IEC publication 60063"

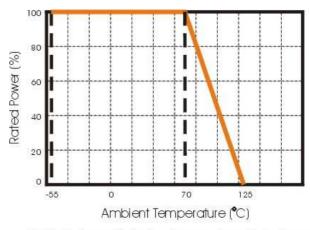
### Derating

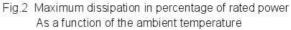
The power that the resistor can dissipate depends on the operating temperature; see Fig.2

# CONSTRUCTION



R1=R2=R3=R4=...=R8





# CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

WA06	w	472_	J	т	L	N
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination	Customer
WA06 : 0602 per W : x8, convex element	W : x8, convex	±5%, E24 : 2 significant	J :±5%	T : 7" Reel taping	code	Code
	digits followed by no. of zeros and a blank	F :±1%		L = Sn base (lead free)	N = Customized	
		10Ω =100_	P : Jumper			
		220Ω =221_				
		Jumper =000_				
		("_" means a blank)				
		±1%, E24+E96: 3 significant digits followed by no. of zeros				
		102Ω =1020				
		37.4KΩ =3742				

1. Reeled tape packaging : 8mm width paper taping 5000pcs per reel.

2. Bulk packaging : 5000pcs per polybag

#### MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



#### SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of **260°C for 10 seconds**. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

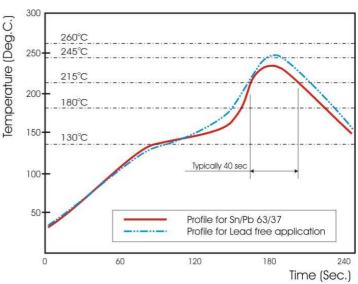


Fig 3. Infrared soldering profile for Chip Resistors array

#### TEST AND REQUIREMENTS

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category LCT/UCT/56(rated temperature range : Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS.

The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied :

Temperature: 15°C to 35°C. Relative humidity: 45% to 75%. Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar).

All soldering tests are performed with midly activated flux.

TEST CONDITION FOR JUMPER ( $0\Omega$ ) Resistance:  $50m\Omega$  max. Rated Current: 1A Peak Current: 3A Operating Temperature: -55 to 125°C

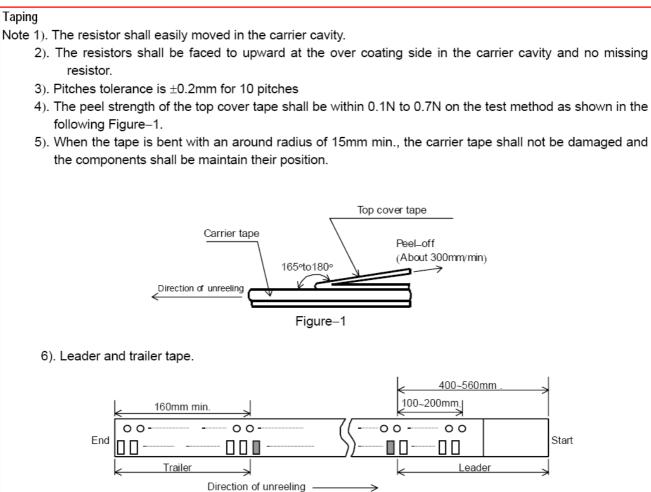


TEST					REQUIREMENT		
1231	PROCEDURE			Resistor	Jumper		
DC resistance (JIS C 5202 5.1)	DC resistance values measured at the test voltages specified below :				Within the specified tolerance	< 50mΩ	
()	Resistance	<100Ω		<10KΩ			
	Test voltage	0.3V		3.0V			
	Resistance	<100KΩ					
	Test voltage	10V					
TCR (JIS C5202 5.2 / IEC115-1 4.8.4.2)	Natural resistance change per change in degree centigrade.				Test temperature – 55~+125°C	N/a	
	$rac{R_2 - R_1}{R_1(t_2 - t_1)} \!\!  imes \! 10^6 \; \text{(ppm/°C)}$				≤±200ppm/°C		
	R1 : Resistance at reference temperature						
	R <sub>2</sub> : Resistance at test temperature						
	t <sub>1</sub> : 25°C						
Short time overload	Permanent resistance change after a 5second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less.			$\Delta$ R/R max. ±(2%+0.10 $\Omega$ )	< 50mΩ		
(JIS C 5202 5.5 / IEC115-1 4.13)							
Resistance to soldering heat	Unmounted chips 10±1 seconds, 260±5°C			no visible damage no visi			
(JIS C 5202 6.4 /				$\Delta$ R/R max. ±(1.0%+0.05 $\Omega$ )	damage, < 50mΩ		
IEC115-1 4.18) Solderability	Termination S	nPh hase	: Unmou	ated chine	good tinning (>95% covered)		
(JIS C 5202 6.5 / IEC115-1 4.17)		SnPb base : Unmounted chips nmersed for $2\pm0.5$ sec. in a solder $5^{\circ}C$		no visible damage			
	Termination Sn base (lead free) : Unmounted chip completely immersed in a lead free solder bath, 235°C±5°C, 2±0.5 sec						
Temperature	1. 30 minutes	1. 30 minutes at -55°C±3°C,			no visible damage	no visible	
cycling (JIS C 5202 7.4 /	2. 10~15minutes at room temperature,				ΔR/R max. ±(1%+0.05Ω)	damage, < 50mΩ	
(JIS C 5202 7.47 IEC115-1 4.19)	3. 30 minutes at +125°±3°C,					< 5011152	
	4. 10~15minutes at room temperature,						
	5 continuous cy						
Load life	70±2°C, 1000 hours, loaded with RCWV Vmax,1.5 hours on and 0.5 hours off		RCWV or	10Ω~1MΩ ±(3%+0.1Ω)	< 50mΩ		
(endurance)							
(JIS C 5202 7.10/ IEC115-1 4.25.1)							
Load life in Humidity	1000 hours, at rated continuous working voltage in humidity chamber controller at 40°C±2°C and			C±2°C and	10Ω~1MΩ ±(3%+0.1Ω)	< 50mΩ	
(JIS C 5202 7.9 / IEC115-1 4.24.2)	90~95% relative hours off	e humidity,	1.5hours of	on and 0.5			

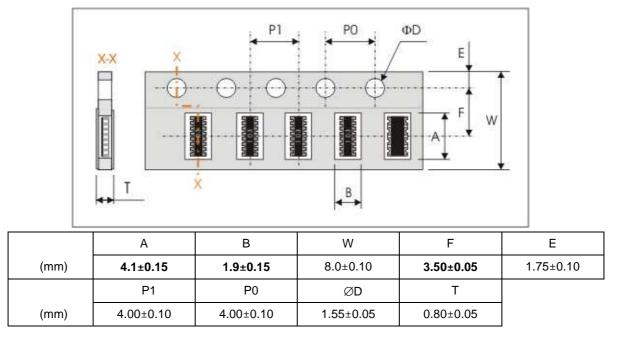


Start

# PACKAGING

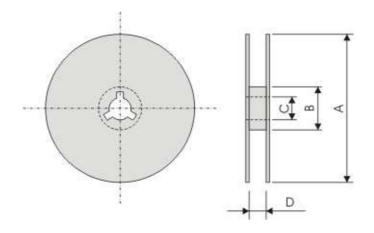


Paper Tape specifications (unit :mm)





#### **Reel dimensions**



Symbol	А	В	С	D
(unit : mm)	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	9.0±0.3